

DFN2020 Plastic-Encapsulate MOSFETS

LJP2025AD2

Silicon P-Channel Power MOSFET

General Description:

The LJP2025AD2 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is DFN2020-6L, which accords with the RoHS standard.

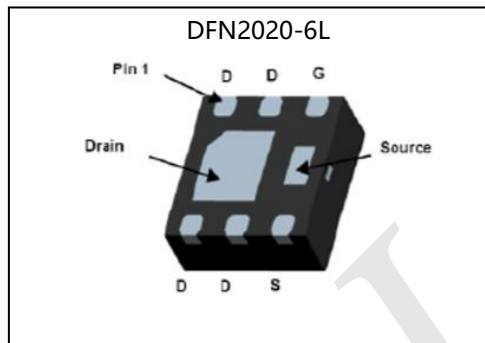
Features:

- $R_{DS(ON)} < 25m\Omega @ V_{GS}=4.5V$ (Typ 19m Ω)
- High density cell design for ultra-low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

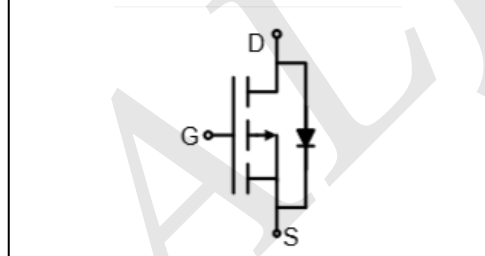
Applications:

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

V_{DSS}	-20	V
I_D	-10	A
P_D	15	W
$R_{DS(ON)type}$	19	m Ω



Inner Equivalent Principium Chart



Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	-20	V
I_D	Continuous Drain Current	-10	A
I_{DM}	Pulsed Drain Current	-40	A
V_{GS}	Gate-to-Source Voltage	± 12	V
P_D	Power Dissipation	15	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	155, -55 to 175	$^\circ C$

Electrical Characteristics (Tc= 25°C unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	-20	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =-20V, V _{GS} = 0V, T _a =25°C	--	--	-1.0	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+12V	--	--	0.1	μA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-12V	--	--	-0.1	μA

ON Characteristics^{a3}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DS(ON)1}	Drain-to-Source On-Resistance	V _{GS} =-4.5V, I _D =-5.0A	--	19	25	mΩ
R _{DS(ON)2}	Drain-to-Source On-Resistance	V _{GS} =-2.5V, I _D =-4.0A	--	25	35	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	-0.4	-0.65	-1.0	V

Pulse width tp≤380μs, δ≤2%

Dynamic Characteristics^{a4}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g _{fs}	Forward Transconductance	V _{DS} =-10V, I _D =-5.0A	--	6.5	8	S
C _{iss}	Input Capacitance	V _{GS} =0V	--	1200	--	pF
C _{oss}	Output Capacitance	V _{DS} =-10V	--	310	--	
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	--	240	--	

Resistive Switching Characteristics^{a4}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-10V	--	25	--	ns
t _r	Rise Time	I _D =-1A	--	30	--	
t _{d(OFF)}	Turn-Off Delay Time	V _{GS} =-4.5V	--	60	--	
t _f	Fall Time	R _G =6.0Ω	--	45	--	
Q _g	Total Gate Charge	V _{DD} =-10V	--	10	--	nC
Q _{gs}	Gate to Source Charge	I _D =-5.0A	--	1.8	--	
Q _{gd}	Gate to Drain ("Miller") Charge	V _{GS} =-4.5V	--	3	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current ^{a2} (Body Diode)		--	--	-10	A
V _{SD}	Diode Forward Voltage ^{a3}	I _S =-5A, V _{GS} =0V	--	--	-1.2	V

Symbol	Parameter	Typ.	Units
R _{θJA}	Junction-to-Ambient	50	°C/W

^{a1}: Repetitive Rating; Pulse width limited by maximum junction temperature.

^{a2}: Surface Mounted on FR4 Board, t≤10sec.

^{a3}: Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.

^{a4}: Guaranteed by design, not subject to production

Characteristics Curve:

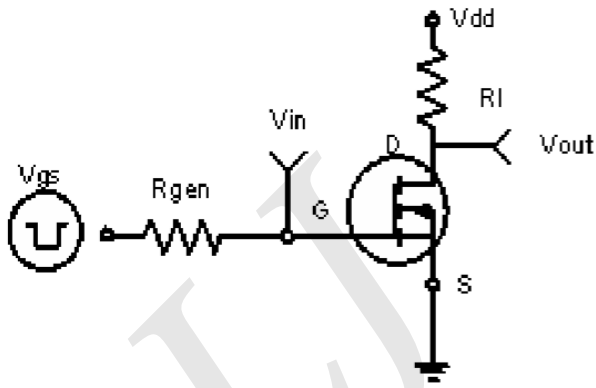


Figure 1 Switching Test Circuit

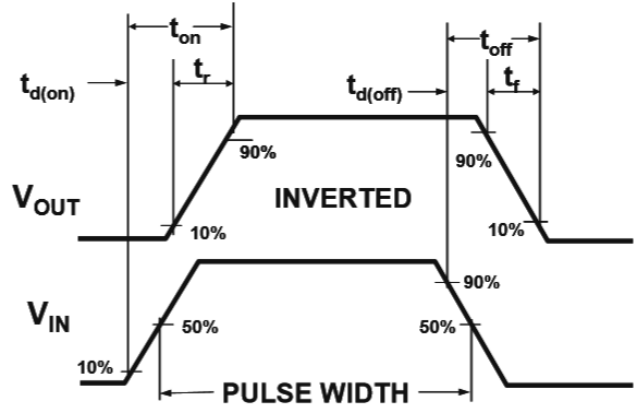


Figure 2 Switching Waveforms

Typical Characteristics

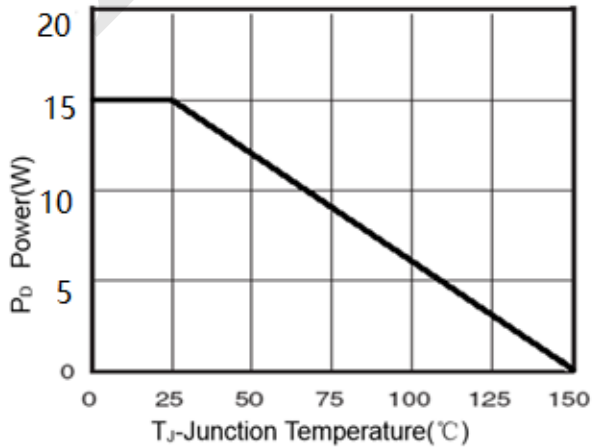


Figure 3 Power Dissipation

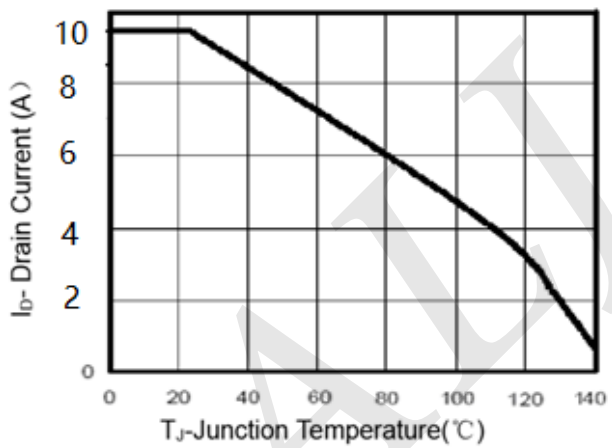


Figure 4 Drain Current

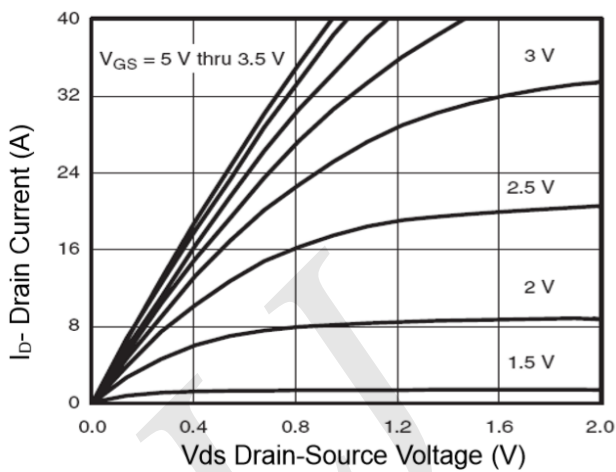


Figure 5 Output Characteristics

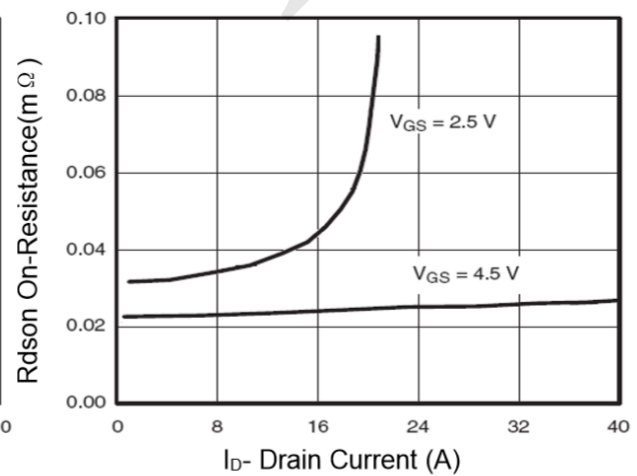


Figure 6 Drain-Source On-Resistance

Typical Characteristics

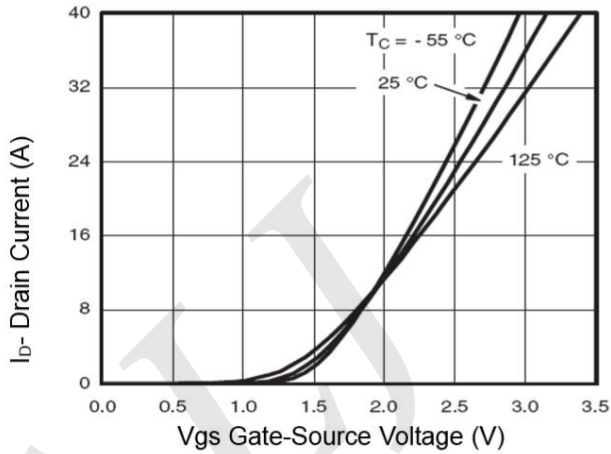


Figure 7 Transfer Characteristics

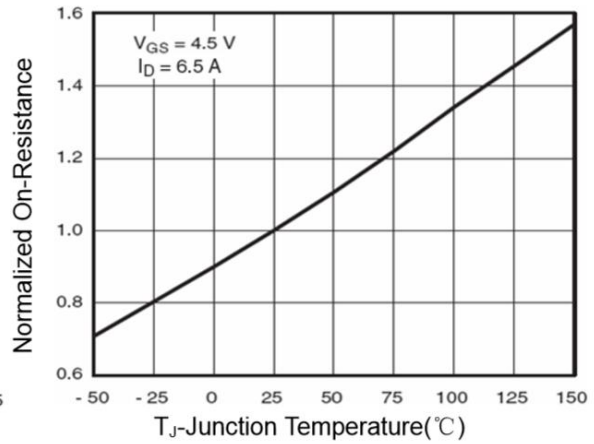


Figure 8 Drain-Source On-Resistance

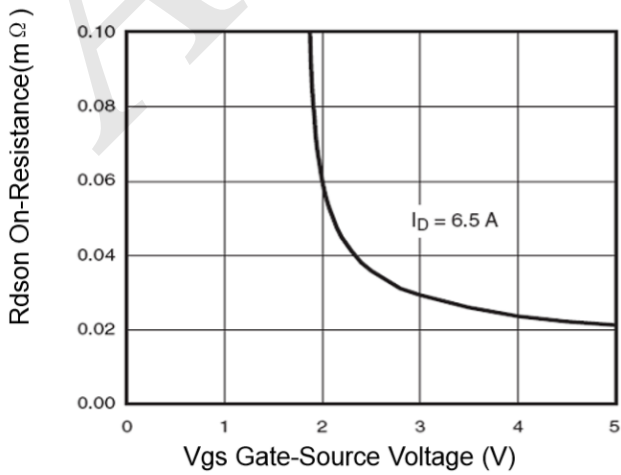


Figure 9 Rdson vs Vgs

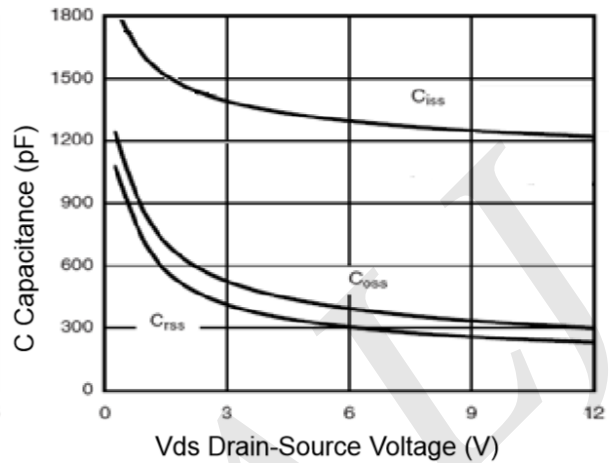


Figure 10 Capacitance vs Vds

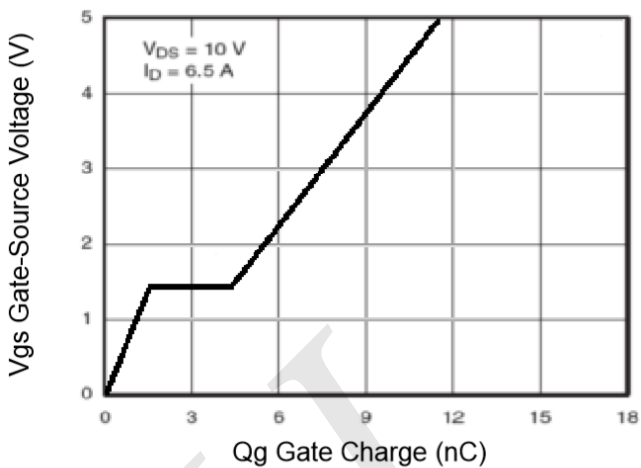


Figure 11 Gate Charge

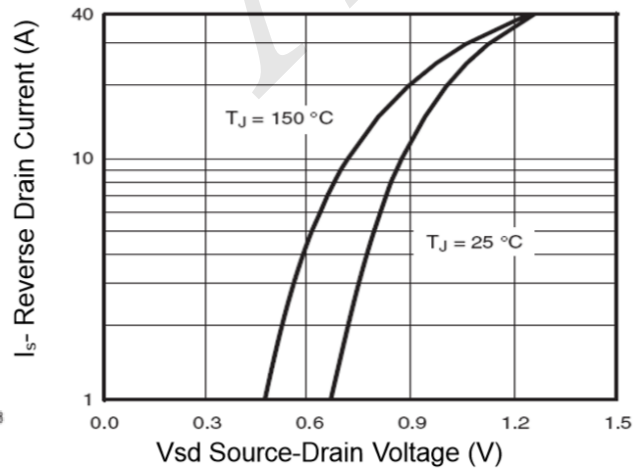


Figure 12 Source- Drain Diode Forward

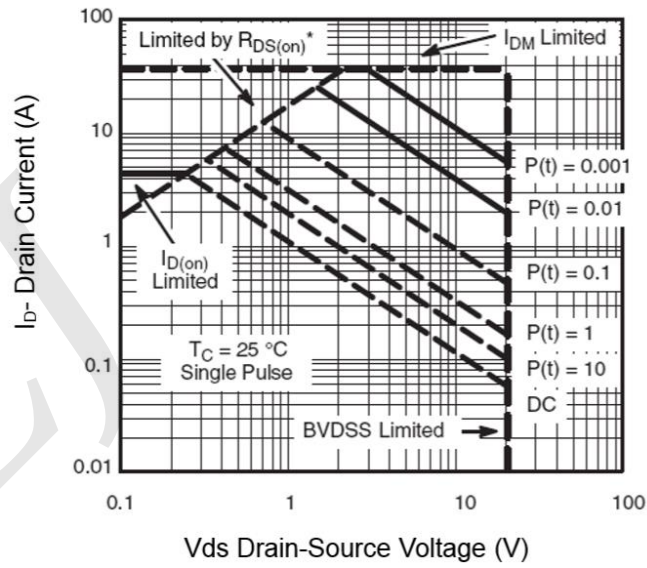


Figure 13 Safe Operation Area

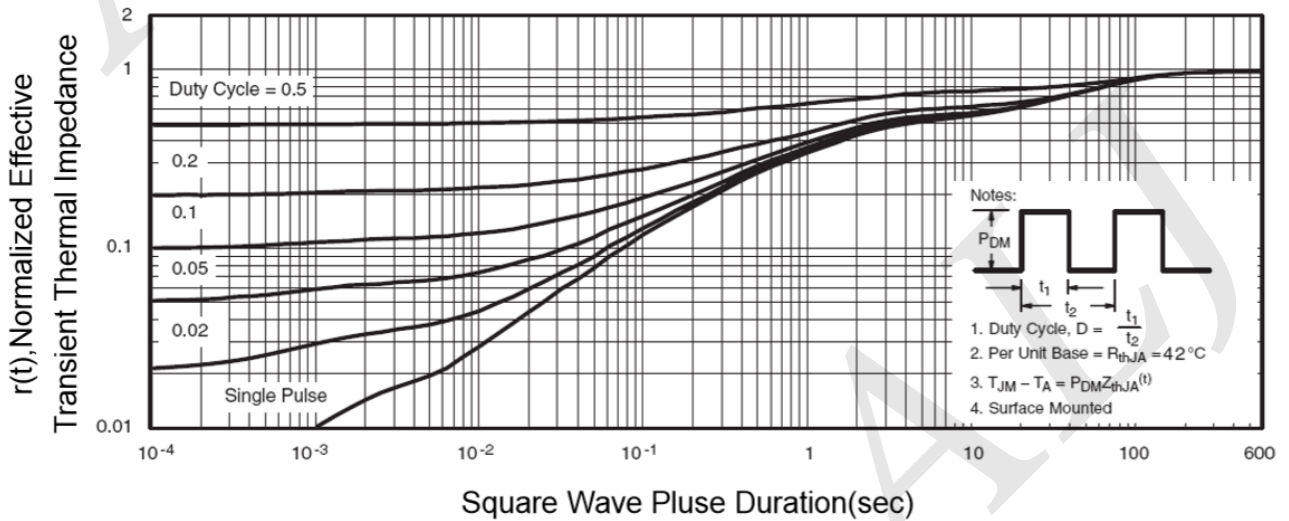
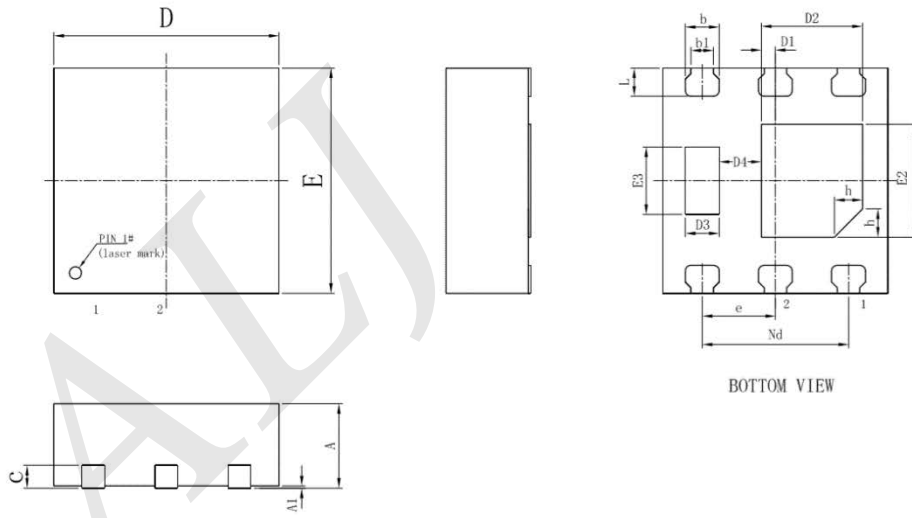


Figure 14 Normalized Maximum Transient Thermal Impedance

Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.45	0.55	0.65
A1	—	0.02	0.05
b	0.25	0.30	0.35
b1	0.20REF		
c	0.1523REF		
D	1.95	2.00	2.05
D1	0.08	0.125	0.18
D2	0.85	0.90	0.95
D3	0.25	0.30	0.35
D4	0.33	0.375	0.43
e	0.65BSC		
Nd	1.30BSC		
E	1.95	2.00	2.05
E2	0.95	1.00	1.05
E3	0.55	0.60	0.65
L	0.20	0.25	0.30
h	0.25REF		